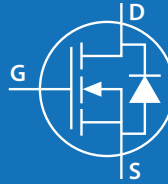


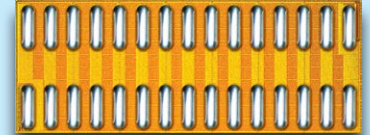
EPC2024 – Enhancement Mode Power Transistor

 V_{DS} , 40 V $R_{DS(on)}$, 1.5 m Ω I_D , 90 A

Revised June 16, 2025

Gallium Nitride's exceptionally high electron mobility and low temperature coefficient allows very low $R_{DS(on)}$, while its lateral device structure and majority carrier diode provide exceptionally low Q_G and zero Q_{RR} . The end result is a device that can handle tasks where very high switching frequency, and low on-time are beneficial as well as those where on-state losses dominate.

Questions:
Ask a GaN
Expert



Die size: 6.05 x 2.3 mm

EPC2024 eGaN® FETs are supplied only in passivated die form with solder bumps.

Applications

- High speed DC-DC conversion
- Motor drive
- Industrial automation
- Synchronous rectification
- Inrush protection
- Point-of-Load (POL) converters

Maximum Ratings			
PARAMETER		VALUE	UNIT
V_{DS}	Drain-to-Source Voltage (Continuous)	40	V
	Drain-to-Source Voltage (up to 10,000 5 ms pulses at 150°C)	48	
I_D	Continuous ($T_A = 25^\circ\text{C}$, $R_{\theta JA} = 6^\circ\text{C/W}$)	90	A
	Pulsed (25°C, $T_{PULSE} = 300 \mu\text{s}$)	560	
V_{GS}	Gate-to-Source Voltage	6	V
	Gate-to-Source Voltage	-4	
T_J	Operating Temperature	-40 to 150	$^\circ\text{C}$
T_{STG}	Storage Temperature	-55 to 150	

Thermal Characteristics			
PARAMETER		TYP	UNIT
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.4	$^\circ\text{C/W}$
$R_{\theta JB}$	Thermal Resistance, Junction-to-Board	1.1	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1)	42	

Note 1: $R_{\theta JA}$ is determined with the device mounted on one square inch of copper pad, single layer 2 oz copper on FR4 board. See https://epc-co.com/epc/documents/product-training/Appnote_Thermal_Performance_of_eGaN_FETs.pdf for details.

Static Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise stated)						
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
BV_{DSS}	Drain-to-Source Voltage	$V_{GS} = 0\text{ V}$, $I_D = 1.1\text{ mA}$	40			V
I_{DSS}	Drain-Source Leakage	$V_{GS} = 0\text{ V}$, $V_{DS} = 32\text{ V}$		0.1	0.9	mA
I_{GSS}	Gate-to-Source Forward Leakage	$V_{GS} = 5\text{ V}$		1	9	mA
	Gate-to-Source Reverse Leakage	$V_{GS} = -4\text{ V}$		0.1	0.9	mA
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 19\text{ mA}$	0.8	1.4	2.5	V
$R_{DS(on)}$	Drain-Source On Resistance	$V_{GS} = 5\text{ V}$, $I_D = 37\text{ A}$		1.2	1.5	m Ω
V_{SD}	Source-Drain Forward Voltage [#]	$V_{GS} = 0\text{ V}$, $I_S = 0.5\text{ A}$		1.8		V

[#] Defined by design. Not subject to production test.

All measurements were done with substrate connected to source.

Scan QR code or click link below for more information including reliability reports, device models, demo boards!



<https://l.ead.me/EPC2024>

Dynamic Characteristics[#] ($T_J = 25^\circ\text{C}$ unless otherwise stated)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
C_{ISS}	Input Capacitance	$V_{GS} = 0\text{ V}, V_{DS} = 20\text{ V}$		1920	2300	pF
C_{OSS}	Output Capacitance			1620	2430	
C_{RSS}	Reverse Transfer Capacitance			29		
$C_{OSS(ER)}$	Effective Output Capacitance, Energy Related (Note 2)	$V_{GS} = 0\text{ V}, V_{DS} = 0\text{ to }20\text{ V}$		2050		pF
$C_{OSS(TR)}$	Effective Output Capacitance, Time Related (Note 3)			2240		
R_G	Gate Resistance			0.3		Ω
Q_G	Total Gate Charge	$V_{GS} = 5\text{ V}, V_{DS} = 20\text{ V}, I_D = 37\text{ A}$		18	24	nC
Q_{GS}	Gate-to-Source Charge	$V_{DS} = 20\text{ V}, I_D = 37\text{ A}$		5.1		
Q_{GD}	Gate-to-Drain Charge			2.4		
$Q_{G(TH)}$	Gate Charge at Threshold			3.8		
Q_{OSS}	Output Charge	$V_{GS} = 0\text{ V}, V_{DS} = 20\text{ V}$		45	68	
Q_{RR}	Source-Drain Recovery Charge			0		

[#] Defined by design. Not subject to production test.

All measurements were done with substrate connected to source.

Note 2: $C_{OSS(ER)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 50% BV_{DSS} .

Note 3: $C_{OSS(TR)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 50% BV_{DSS} .

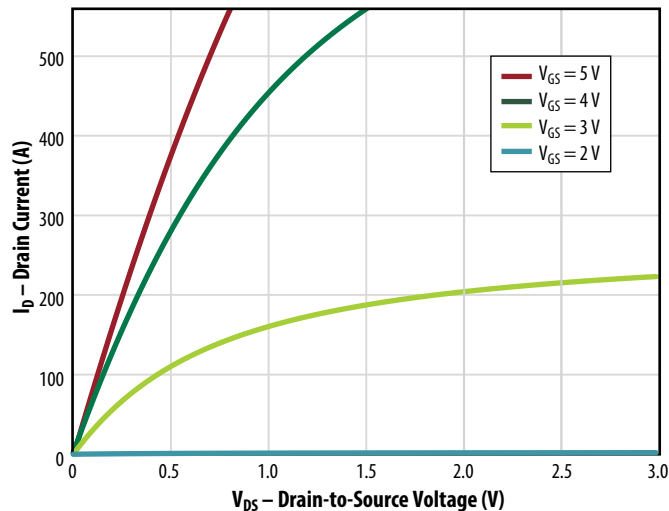
Figure 1: Typical Output Characteristics at 25°C 

Figure 2: Typical Transfer Characteristics

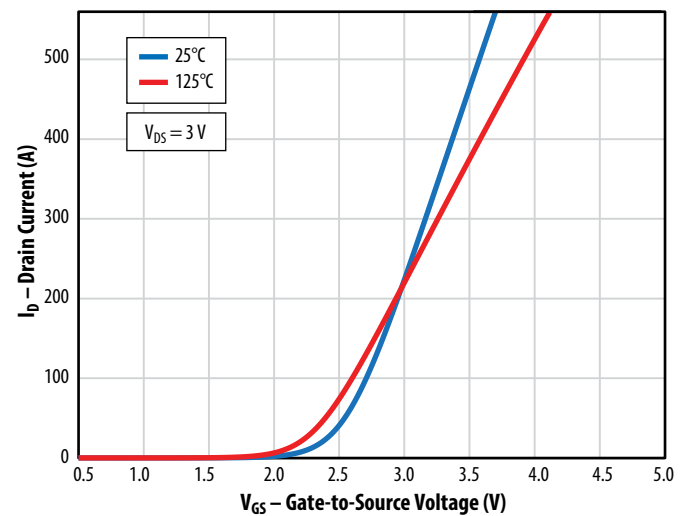
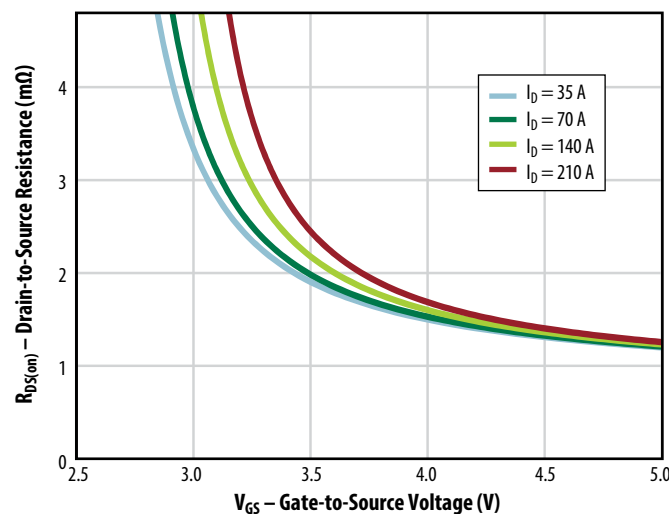
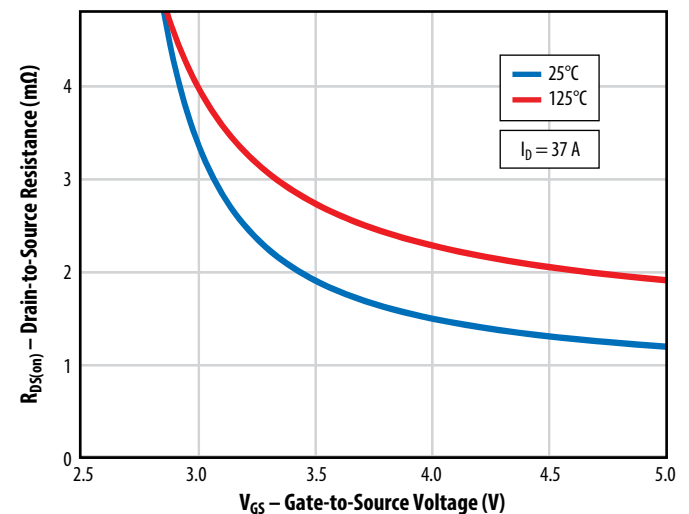
Figure 3: Typical $R_{DS(on)}$ vs. V_{GS} for Various Drain CurrentsFigure 4: Typical $R_{DS(on)}$ vs. V_{GS} for Various Temperatures

Figure 5a: Typical Capacitance (Linear Scale)

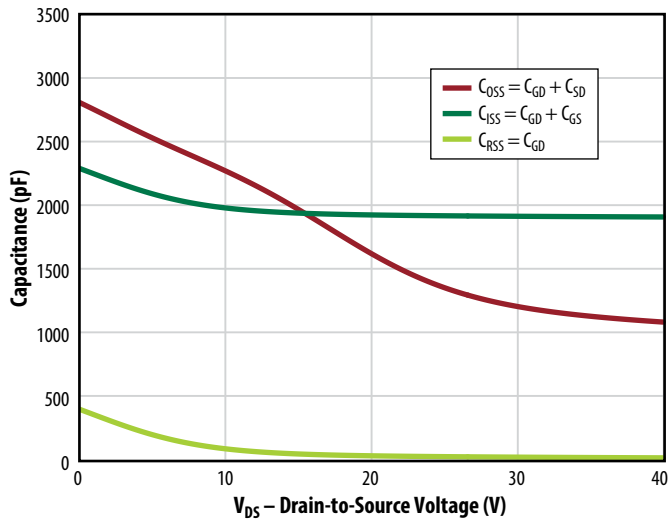


Figure 5b: Typical Capacitance (Log Scale)

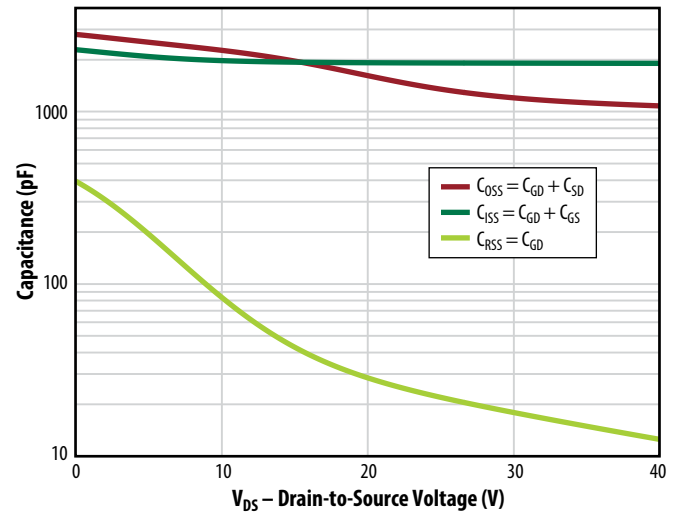


Figure 6: Typical Gate Charge

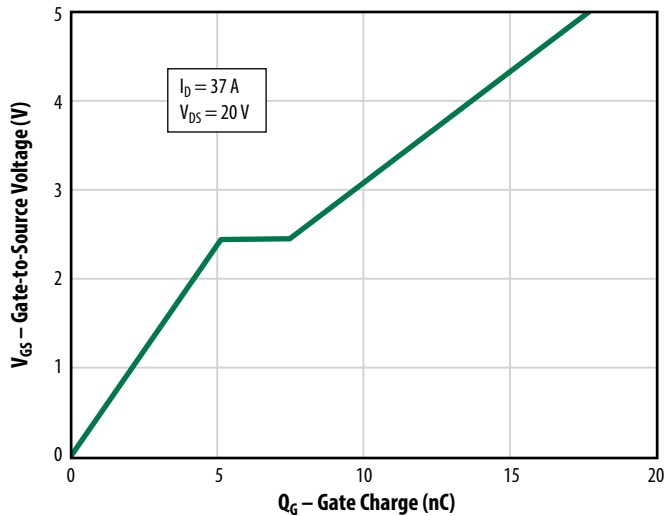
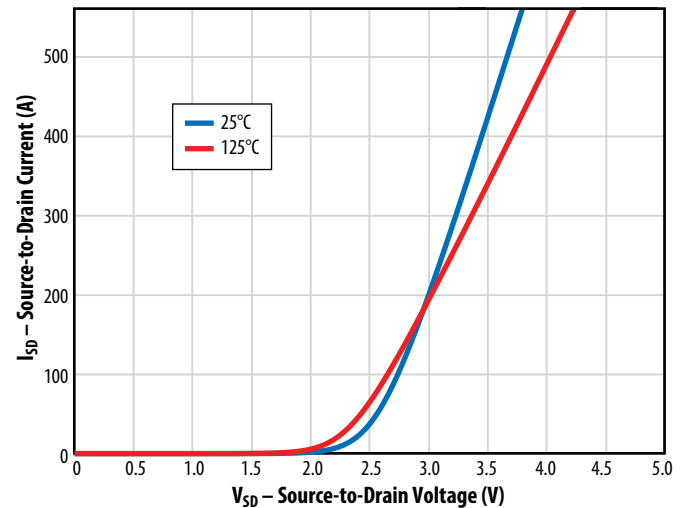


Figure 7: Typical Reverse Drain-Source Characteristics



Note: Negative gate drive voltage increases the reverse drain-source voltage.
EPC recommends 0 V for OFF.

Figure 8: Typical Normalized On-State Resistance vs. Temp.

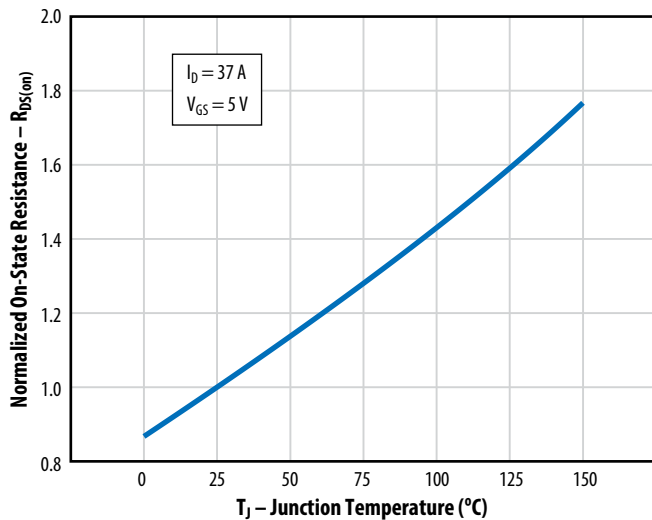


Figure 9: Typical Normalized Threshold Voltage vs. Temp.

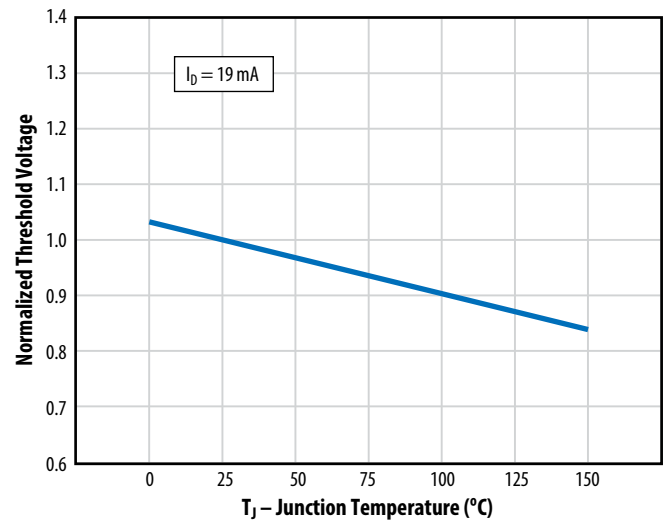


Figure 10: Typical Gate Leakage Current

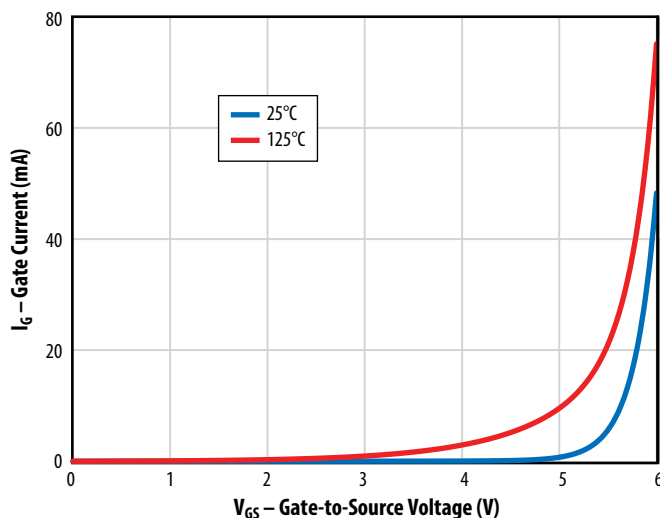


Figure 11: Typical Transient Thermal Response Curves

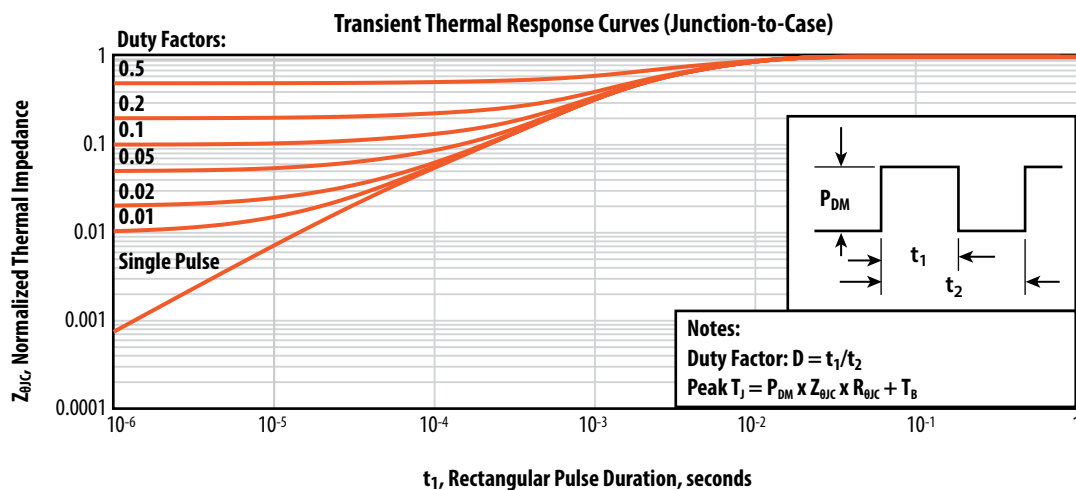
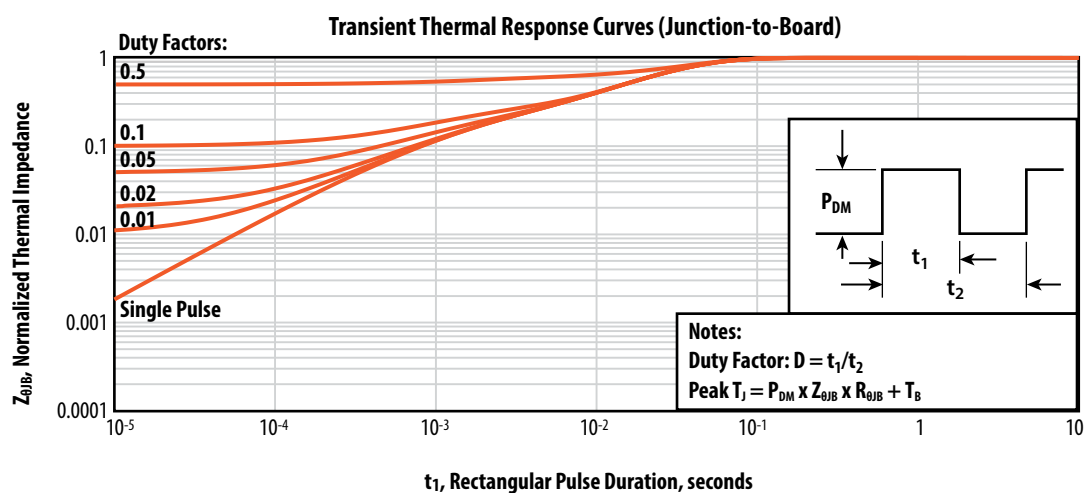
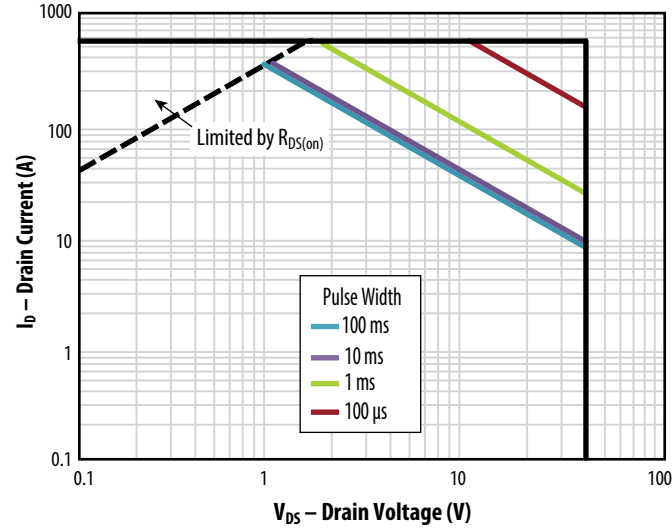
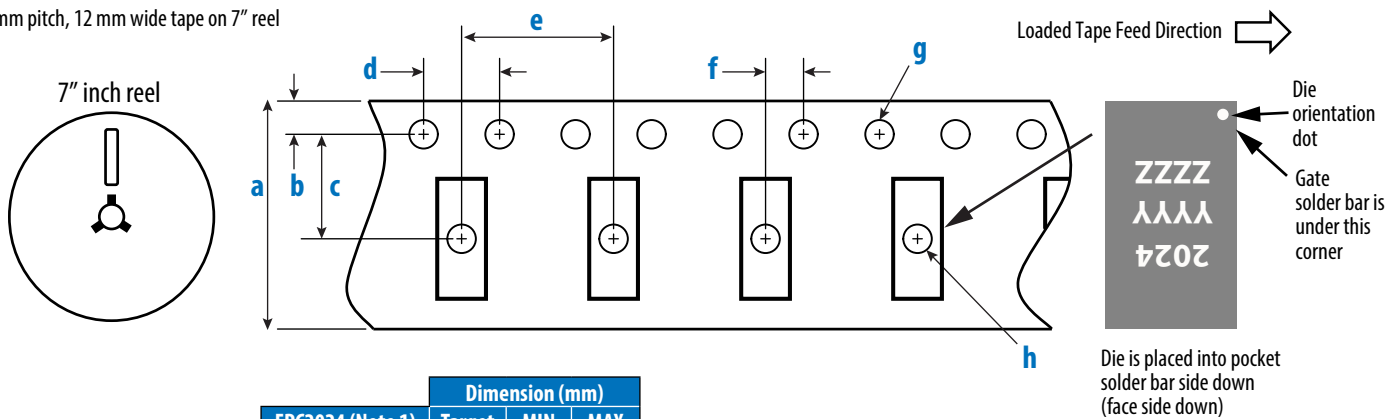


Figure 12: Safe Operating Area



TAPE AND REEL CONFIGURATION

8 mm pitch, 12 mm wide tape on 7" reel

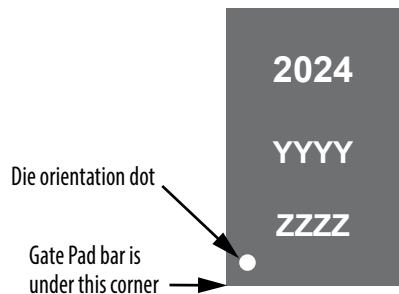


	Dimension (mm)		
EPC2024 (Note 1)	Target	MIN	MAX
a	12.00	11.90	12.30
b	1.75	1.65	1.85
c (Note 2)	5.50	5.45	5.55
d	4.00	3.90	4.10
e	8.00	7.90	8.10
f (Note 2)	2.00	1.95	2.05
g	1.50	1.50	1.60
h	1.50	1.50	1.75

Note 1: MSL 1 (moisture sensitivity level 1) classified according to IPC/JEDEC industry standard.

Note 2: Pocket position is relative to the sprocket hole measured as true position of the pocket, not the pocket hole.

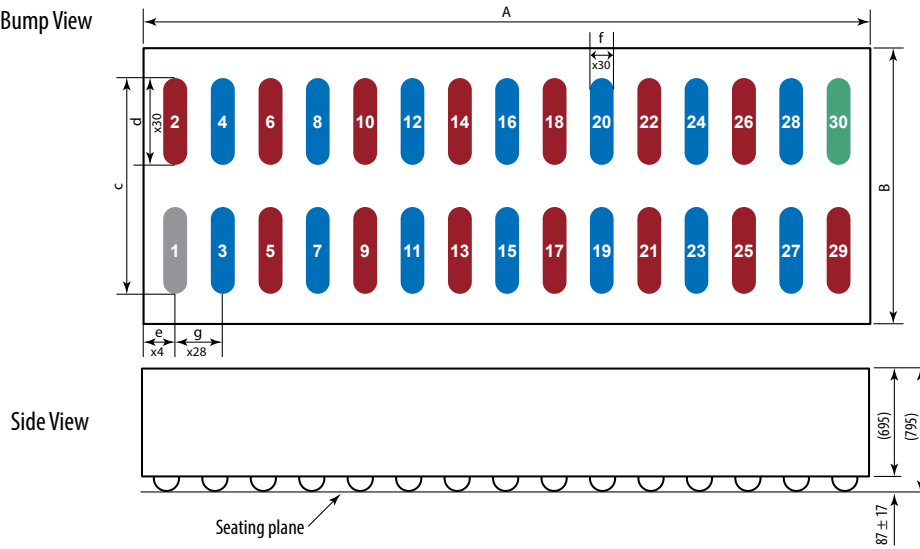
DIE MARKINGS



Part Number	Laser Markings		
	Part # Marking Line 1	Lot_Date Code Marking Line 2	Lot_Date Code Marking Line 3
EPC2024	2024	YYYY	ZZZZ

DIE OUTLINE

Solder Bump View



DIM	Micrometers		
	MIN	Nominal	MAX
A	6020	6050	6080
B	2270	2300	2330
C	2047	2050	2053
D	717	720	723
E	210	225	240
F	195	200	205
G	400	400	400

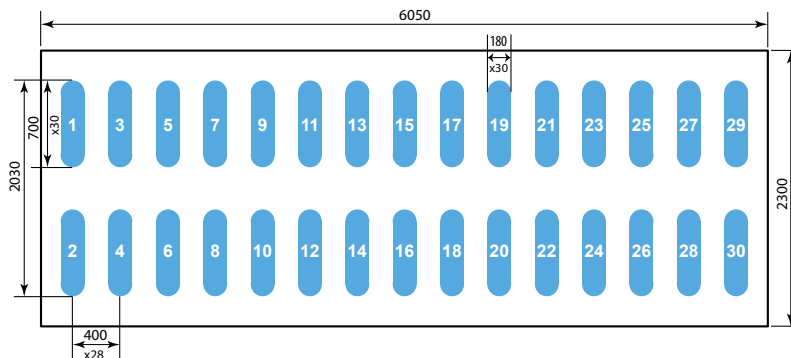
Pad 1 is Gate;

Pads 2, 5, 6, 9, 10, 13, 14, 17, 18, 21, 22, 25, 26, 29 are Source;

Pads 3, 4, 7, 8, 11, 12, 15, 16, 19, 20, 23, 24, 27, 28 are Drain;

Pad 30 is Substrate.*

*Substrate pin should be connected to Source

RECOMMENDED LAND PATTERN(units in μm)

Land pattern is solder mask defined.

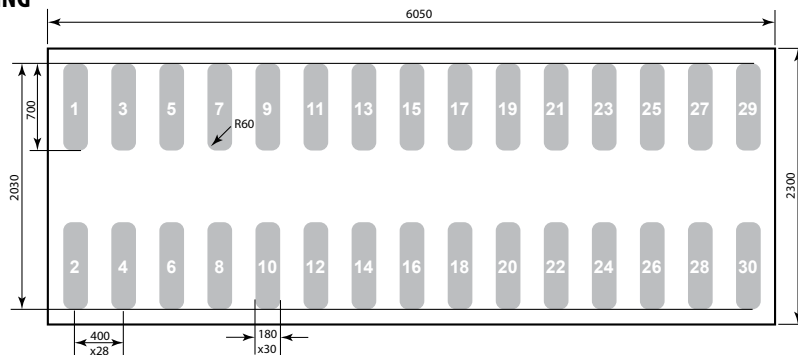
Pad 1 is Gate;

Pads 2, 5, 6, 9, 10, 13, 14, 17, 18, 21, 22, 25, 26, 29 are Source;

Pads 3, 4, 7, 8, 11, 12, 15, 16, 19, 20, 23, 24, 27, 28 are Drain;

Pad 30 is Substrate.*

*Substrate pin should be connected to Source

RECOMMENDED STENCIL DRAWING(units in μm)Recommended stencil should be 4 mil (100 μm) thick, must be laser cut, openings per drawing.

Intended for use with SAC305 Type 4 solder, reference 88.5% metals content.

Additional assembly resources available at <https://epc-co.com/epc/design-support>

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